

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S4	768123	pin\$1	US-PGPUB; USPAT	OR	OFF	2004/12/10 14:24
S5	8912	solder adj joint\$1	US-PGPUB; USPAT	OR	OFF	2004/12/10 14:24
S6	327403	pad\$1	US-PGPUB; USPAT	OR	OFF	2004/12/10 14:25
S7	88	encapsulat\$3 near2 S5	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:57
S8	16	S4 and S5 and S6 and S7	US-PGPUB; USPAT	OR	OFF	2004/12/10 14:57
S9	18501	solder adj (ball\$1 or bump\$1)	US-PGPUB; USPAT	OR	OFF	2004/12/10 14:57
S10	1052	S4 and S5 and S9	US-PGPUB; USPAT	OR	OFF	2004/12/10 15:16
S11	18	S7 and S10	US-PGPUB; USPAT	OR	OFF	2004/12/10 14:58
S13	916	S4 and S5 and S6 and S9	US-PGPUB; USPAT	OR	OFF	2004/12/10 15:19
S14	448508	ball adj grid array or BGA	US-PGPUB; USPAT	OR	OFF	2004/12/10 15:19
S15	43	S7 and S14	US-PGPUB; USPAT	OR	OFF	2004/12/10 15:27
S16	5329	i/o adj S4	US-PGPUB; USPAT	OR	OFF	2004/12/10 15:27
S17	3794	input/output adj S4	US-PGPUB; USPAT	OR	OFF	2004/12/10 15:28
S18	5514	input adj output adj S4	US-PGPUB; USPAT	OR	OFF	2004/12/10 15:28
S19	1	(S6 same S9 same (S16 or S17 or S18)) and S7	US-PGPUB; USPAT	OR	OFF	2004/12/10 15:30
S20	78	(S6 same S9 same (S16 or S17 or S18))	US-PGPUB; USPAT	OR	OFF	2004/12/10 15:31
S21	0	encapsulat\$3 near2 S5	IBM_TDB	OR	OFF	2004/12/10 17:30
S22	1	encapsulated adj solder adj joint\$1	IBM_TDB	OR	OFF	2004/12/10 17:51
S23	0	seal\$3 near2 S5	IBM_TDB	OR	OFF	2004/12/10 17:52
S24	0	seal\$3 near2 S9	IBM_TDB	OR	OFF	2004/12/10 17:52
S25	92	seal\$3 near2 S5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/10 17:54

S26	27	sealed near2 S5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/10 17:55
S27	11	(encapsulat\$3 near2 S9) and (S16 or S17 or S18)	US-PGPUB; USPAT	OR	OFF	2004/12/10 18:08
S28	340	encapsulat\$3 near2 S9	US-PGPUB; USPAT	OR	OFF	2004/12/10 18:16
S29	5708	solder adj joint	US-PGPUB; USPAT	OR	OFF	2004/12/10 18:17
S30	1	encapsulat\$3 near2 (S16 or S17 or S18)	US-PGPUB; USPAT	OR	OFF	2004/12/10 18:19
S31	419	encapsulat\$3 near2 S4	US-PGPUB; USPAT	OR	OFF	2004/12/10 18:20
S32	157629	encapsulat\$3	US-PGPUB; USPAT	OR	OFF	2004/12/10 18:20
S33	217	S4 same S9 same S32	US-PGPUB; USPAT	OR	OFF	2004/12/10 18:28
S34	525	228/175.ccls.	US-PGPUB; USPAT	OR	OFF	2004/12/10 18:30
S35	374	257/697.ccls.	US-PGPUB; USPAT	OR	OFF	2004/12/10 22:07
S36	1113	438/613.ccls.	US-PGPUB; USPAT	OR	OFF	2004/12/10 22:07
S37	3590	underfill	US-PGPUB; USPAT	OR	OFF	2004/12/10 22:07
S38	166	S36 and S37	US-PGPUB; USPAT	OR	OFF	2004/12/10 23:36
S39	6765	solder adj (ball\$1 or bump\$1)	US-PGPUB	OR	OFF	2004/12/10 23:37
S40	1884	underfill\$3	US-PGPUB	OR	OFF	2004/12/10 23:37
S41	49685	encapsulat\$3	US-PGPUB	OR	OFF	2004/12/10 23:37
S42	1492	S39 same (S40 or S41)	US-PGPUB	OR	OFF	2004/12/10 23:38
S43	77343	pad\$1	US-PGPUB	OR	OFF	2004/12/10 23:38
S44	1297	S42 and S43	US-PGPUB	OR	OFF	2004/12/10 23:39
S45	1814	solder adj joint\$1	US-PGPUB	OR	OFF	2004/12/10 23:43
S46	840	(S40 or S41) same S39 same S43	US-PGPUB	OR	OFF	2004/12/11 00:00
S47	296	((S40 or S41) near3 S39) and S43	US-PGPUB	OR	OFF	2004/12/11 00:38
S48	5671	flip adj chip	US-PGPUB	OR	OFF	2004/12/11 00:39
S49	217	S48 and ((S40 or S41) same S45)	US-PGPUB	OR	OFF	2004/12/11 00:47
S50	122924	pin\$1	US-PGPUB	OR	OFF	2004/12/11 00:47
S51	123	(S40 or S41) and S45 and S48 and S50	US-PGPUB	OR	OFF	2004/12/11 01:02

S52	585	S39 and (S40 or S41) and S43 and S48 and S50	US-PGPUB	OR	OFF	2004/12/11 01:03
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